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Product Change Notification - JAON-12WMVJ562

Date: 14 Dec 2016

Product Category: SMSC; Touch Sensing Technologies; 8-bit Microcontrollers; 16-bit Microcontrollers and Digital Signal Controllers

Notification subject: CCB 2698.001-.005 Final Notice: Qualification of CuPdAu bond wire in selected products of the 200K wafer technology available in 44L QFN, 28L QFN-S, 28L QFN, 20L QFN and 16L QFN packages at MTAI site

Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 44L QFN (8x8mm), 28L QFN-S (6x6mm), 28L QFN (6x6mm), 20L QFN (4x4mm), 16L QFN (4x4mm) and 16L QFN (3x3mm) packages at MTAI assembly site.

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

| | Pre Change | Post Change |
|----------------------------------|------------|-------------|
| Assembly Site | MTAI | MTAI |
| Wire material | Au wire | CuPdAu wire |
| Die attach material | 3280 | 3280 |
| Molding compound material | G700LTD | G700LTD |
| Lead frame material | CDA194 | CDA194 |

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:
In Progress

Estimated First Ship Date:
March 14, 2017 (Date code: 1711)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

| | December 2016 | | | | | | March 2017 | | | | |
|-------------------------------|---------------|----|----|----|----|--|------------|----|----|----|----|
| Workweek | 48 | 49 | 50 | 51 | 52 | | 09 | 10 | 11 | 12 | 13 |
| Qual Report Availability | | | X | | | | | | | | |
| Final PCN Issue Date | | | X | | | | | | | | |
| Estimated Implementation Date | | | | | | | | | X | | |

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
December 14, 2016: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_JAON-12WMVJ562_Qual_Report.pdf](#)
 - [PCN_JAON-12WMVJ562_Affected CPN.pdf](#)
 - [PCN_JAON-12WMVJ562_Affected CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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JAON-12WMVJ562 - CCB 2698.001-.005 Final Notice: Qualification of CuPdAu bond wire in selected products of the 200K wafer technology available in 44L, 28L, 20L and 16L QFN and 28L QFN-S packages at MTAI assembly site

Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|---------------------|
| CATALOG_PART_NBR |
| HA2223-I/ML |
| HA2223T-I/ML |
| MCP2221A-I/ML |
| MCP2221AT-I/ML |
| MCP2221-I/ML |
| MCP2221T-I/ML |
| MTCH105-I/ML |
| MTCH105T-I/ML |
| PIC16F1454-E/ML |
| PIC16F1454-I/ML |
| PIC16F1454T-I/ML |
| PIC16F1455-E/ML |
| PIC16F1455-I/ML |
| PIC16F1455-I/MLC02 |
| PIC16F1455T-I/ML |
| PIC16F1455T-I/MLC02 |
| PIC16F1459-E/ML |
| PIC16F1459-I/ML |
| PIC16F1459-I/MLC01 |
| PIC16F1459T-I/ML |
| PIC16F1459T-I/ML020 |
| PIC16F1459T-I/MLC01 |
| PIC16F1503-E/MG |
| PIC16F1503-I/MG |
| PIC16F1503-I/MG031 |
| PIC16F1503-I/MGC02 |
| PIC16F1503T-E/MG |
| PIC16F1503T-E/MG033 |
| PIC16F1503T-E/MG035 |
| PIC16F1503T-E/MG039 |
| PIC16F1503T-I/MG |
| PIC16F1503T-I/MG022 |
| PIC16F1503T-I/MG027 |
| PIC16F1503T-I/MG028 |
| PIC16F1503T-I/MG029 |
| PIC16F1503T-I/MG030 |
| PIC16F1503T-I/MG031 |
| PIC16F1503T-I/MG032 |
| PIC16F1503T-I/MG035 |
| PIC16F1503T-I/MG037 |
| PIC16F1503T-I/MG043 |
| PIC16F1503T-I/MG044 |
| PIC16F1503T-I/MG048 |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|---------------------|
| CATALOG_PART_NBR |
| PIC16F1503T-I/MGC02 |
| PIC16F1507-E/ML |
| PIC16F1507-I/ML |
| PIC16F1507T-E/ML |
| PIC16F1507T-I/ML |
| PIC16F1508-E/ML |
| PIC16F1508-I/ML |
| PIC16F1508T-E/ML |
| PIC16F1508T-E/ML025 |
| PIC16F1508T-I/ML |
| PIC16F1508T-I/MLOPP |
| PIC16F1509-E/ML |
| PIC16F1509-I/ML |
| PIC16F1509T-E/ML |
| PIC16F1509T-I/ML |
| PIC16F1613-E/ML |
| PIC16F1613-I/ML |
| PIC16F1613T-I/ML |
| PIC16F1614-E/ML |
| PIC16F1614-I/ML |
| PIC16F1614T-I/ML |
| PIC16F1615-E/ML |
| PIC16F1615-I/ML |
| PIC16F1615T-I/ML |
| PIC16F1618-E/ML |
| PIC16F1618-I/ML |
| PIC16F1618T-I/ML |
| PIC16F1619-E/ML |
| PIC16F1619-I/ML |
| PIC16F1619T-I/ML |
| PIC16F1703-E/ML |
| PIC16F1703-I/ML |
| PIC16F1703T-I/ML |
| PIC16F1704-E/ML |
| PIC16F1704-I/ML |
| PIC16F1704T-E/ML |
| PIC16F1704T-I/ML |
| PIC16F1705-E/ML |
| PIC16F1705-I/ML |
| PIC16F1705T-E/ML |
| PIC16F1705T-I/ML |
| PIC16F1707-E/ML |
| PIC16F1707-I/ML |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|---------------------|
| CATALOG_PART_NBR |
| PIC16F1707T-I/ML |
| PIC16F1708-E/ML |
| PIC16F1708-E/ML028 |
| PIC16F1708-I/ML |
| PIC16F1708T-E/ML |
| PIC16F1708T-E/ML025 |
| PIC16F1708T-E/ML026 |
| PIC16F1708T-E/ML027 |
| PIC16F1708T-E/ML028 |
| PIC16F1708T-E/ML030 |
| PIC16F1708T-I/ML |
| PIC16F1709-E/ML |
| PIC16F1709-I/ML |
| PIC16F1709-I/ML020 |
| PIC16F1709T-E/ML |
| PIC16F1709T-I/ML |
| PIC16F1709T-I/ML020 |
| PIC16F1713-E/ML |
| PIC16F1713-I/ML |
| PIC16F1713T-I/ML |
| PIC16F1716-E/ML |
| PIC16F1716-I/ML |
| PIC16F1716T-I/ML |
| PIC16F1717-E/ML |
| PIC16F1717-I/ML |
| PIC16F1717T-I/ML |
| PIC16F1718-E/ML |
| PIC16F1718-I/ML |
| PIC16F1718T-I/ML |
| PIC16F1719-E/ML |
| PIC16F1719-I/ML |
| PIC16F1719T-I/ML |
| PIC16F1764-E/ML |
| PIC16F1764-I/ML |
| PIC16F1764T-E/ML |
| PIC16F1764T-I/ML |
| PIC16F1765-E/ML |
| PIC16F1765-I/ML |
| PIC16F1765T-I/ML |
| PIC16F1768-E/ML |
| PIC16F1768-I/ML |
| PIC16F1768T-E/ML |
| PIC16F1768T-I/ML |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|---------------------|
| CATALOG_PART_NBR |
| PIC16F1769-E/ML |
| PIC16F1769-I/ML |
| PIC16F1769T-E/ML |
| PIC16F1769T-I/ML |
| PIC16F1777-E/ML |
| PIC16F1777-I/ML |
| PIC16F1777T-I/ML |
| PIC16F1779-E/ML |
| PIC16F1779-I/ML |
| PIC16F1779T-I/ML |
| PIC16F1782-E/ML |
| PIC16F1782-I/ML |
| PIC16F1782T-E/ML |
| PIC16F1782T-I/ML |
| PIC16F1783-E/ML |
| PIC16F1783-I/ML |
| PIC16F1783T-E/ML |
| PIC16F1783T-I/ML |
| PIC16F1784-E/ML |
| PIC16F1784-I/ML |
| PIC16F1784T-I/ML |
| PIC16F1786-E/ML |
| PIC16F1786-I/ML |
| PIC16F1786T-I/ML |
| PIC16F1787-E/ML |
| PIC16F1787-I/ML |
| PIC16F1787T-I/ML |
| PIC16F1787T-I/ML020 |
| PIC16F1788-E/ML |
| PIC16F1788-I/ML |
| PIC16F1788T-E/ML |
| PIC16F1788T-I/ML |
| PIC16F1789-E/ML |
| PIC16F1789-I/ML |
| PIC16F1789T-I/ML |
| PIC16F1823-E/ML |
| PIC16F1823-I/ML |
| PIC16F1823-I/ML029 |
| PIC16F1823-I/MLC03 |
| PIC16F1823-I/MLLS1 |
| PIC16F1823T-E/ML |
| PIC16F1823T-I/ML |
| PIC16F1823T-I/ML029 |

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Affected Catalog Part Numbers (CPN)

| |
|---------------------|
| PCN_JAON-12WMVJ562 |
| CATALOG_PART_NBR |
| PIC16F1823T-I/MLC03 |
| PIC16F1823T-I/MLLS1 |
| PIC16F1824-E/ML |
| PIC16F1824-I/ML |
| PIC16F1824T-E/ML |
| PIC16F1824T-I/ML |
| PIC16F1824T-I/MLC01 |
| PIC16F1824T-I/MLOPP |
| PIC16F1825-E/ML |
| PIC16F1825-H/ML |
| PIC16F1825-I/ML |
| PIC16F1825T-E/ML |
| PIC16F1825T-E/ML031 |
| PIC16F1825T-H/ML |
| PIC16F1825T-I/ML |
| PIC16F1826-E/ML |
| PIC16F1826-I/ML |
| PIC16F1826T-I/ML |
| PIC16F1827-E/ML |
| PIC16F1827-I/ML |
| PIC16F1827T-I/ML |
| PIC16F1828-E/ML |
| PIC16F1828-E/MLC02 |
| PIC16F1828-I/ML |
| PIC16F1828-I/MLC04 |
| PIC16F1828T-E/ML |
| PIC16F1828T-I/ML |
| PIC16F1829-E/ML |
| PIC16F1829-H/ML |
| PIC16F1829-I/ML |
| PIC16F1829-I/ML030 |
| PIC16F1829-I/ML031 |
| PIC16F1829T-E/ML |
| PIC16F1829T-H/ML |
| PIC16F1829T-I/ML |
| PIC16F1829T-I/ML030 |
| PIC16F1829T-I/ML031 |
| PIC16F1847-E/ML |
| PIC16F1847-I/ML |
| PIC16F1847T-I/ML |
| PIC16F1933-E/ML |
| PIC16F1933-I/ML |
| PIC16F1933T-E/ML |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|---------------------|
| CATALOG_PART_NBR |
| PIC16F1933T-I/ML |
| PIC16F1934-E/ML |
| PIC16F1934-I/ML |
| PIC16F1934T-I/ML |
| PIC16F1936-E/ML |
| PIC16F1936-I/ML |
| PIC16F1936-I/MLC02 |
| PIC16F1936T-I/ML |
| PIC16F1937-E/ML |
| PIC16F1937-I/ML |
| PIC16F1937T-I/ML |
| PIC16F1938-E/ML |
| PIC16F1938-I/ML |
| PIC16F1938-I/MLRA2 |
| PIC16F1938T-I/ML |
| PIC16F1938T-I/MLRA2 |
| PIC16F1939-E/ML |
| PIC16F1939-I/ML |
| PIC16F1939T-I/ML |
| PIC16F707-E/ML |
| PIC16F707-I/ML |
| PIC16F707T-I/ML |
| PIC16F720-E/ML |
| PIC16F720-I/ML |
| PIC16F720T-I/ML |
| PIC16F721-E/ML |
| PIC16F721-I/ML |
| PIC16F721T-E/ML |
| PIC16F721T-I/ML |
| PIC16F722A-E/ML |
| PIC16F722A-I/ML |
| PIC16F722AT-I/ML |
| PIC16F722-E/ML |
| PIC16F722-I/ML |
| PIC16F722T-I/ML |
| PIC16F723A-E/ML |
| PIC16F723A-I/ML |
| PIC16F723AT-I/ML |
| PIC16F723-E/ML |
| PIC16F723-I/ML |
| PIC16F723T-E/ML |
| PIC16F723T-I/ML |
| PIC16F724-E/ML |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|----------------------|
| CATALOG_PART_NBR |
| PIC16F724-I/ML |
| PIC16F724T-I/ML |
| PIC16F726-E/ML |
| PIC16F726-I/ML |
| PIC16F726T-I/ML |
| PIC16F727-E/ML |
| PIC16F727-I/ML |
| PIC16F727T-I/ML |
| PIC16LF1454-E/ML |
| PIC16LF1454-I/ML |
| PIC16LF1454T-I/ML |
| PIC16LF1455-E/ML |
| PIC16LF1455-I/ML |
| PIC16LF1455T-I/ML |
| PIC16LF1459-E/ML |
| PIC16LF1459-I/ML |
| PIC16LF1459-I/MLC01 |
| PIC16LF1459-I/MLC02 |
| PIC16LF1459T-I/ML |
| PIC16LF1459T-I/MLC01 |
| PIC16LF1459T-I/MLC02 |
| PIC16LF1503-E/MG |
| PIC16LF1503-I/MG |
| PIC16LF1503-I/MG022 |
| PIC16LF1503-I/MGC02 |
| PIC16LF1503T-E/MG |
| PIC16LF1503T-I/MG |
| PIC16LF1503T-I/MG022 |
| PIC16LF1503T-I/MGC02 |
| PIC16LF1507-E/ML |
| PIC16LF1507-I/ML |
| PIC16LF1507T-I/ML |
| PIC16LF1508-E/ML |
| PIC16LF1508-I/ML |
| PIC16LF1508T-I/ML |
| PIC16LF1509-E/ML |
| PIC16LF1509-I/ML |
| PIC16LF1509T-I/ML |
| PIC16LF1516-E/ML |
| PIC16LF1516-I/ML |
| PIC16LF1516T-I/ML |
| PIC16LF1518-E/ML |
| PIC16LF1518-I/ML |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|--------------------|
| CATALOG_PART_NBR |
| PIC16LF1518T-I/ML |
| PIC16LF1554-E/ML |
| PIC16LF1554-I/ML |
| PIC16LF1554T-I/ML |
| PIC16LF1559-E/ML |
| PIC16LF1559-I/ML |
| PIC16LF1559T-I/ML |
| PIC16LF1613-E/ML |
| PIC16LF1613-I/ML |
| PIC16LF1613T-I/ML |
| PIC16LF1614-E/ML |
| PIC16LF1614-I/ML |
| PIC16LF1614T-I/ML |
| PIC16LF1615-E/ML |
| PIC16LF1615-I/ML |
| PIC16LF1615T-I/ML |
| PIC16LF1618-E/ML |
| PIC16LF1618-I/ML |
| PIC16LF1618T-I/ML |
| PIC16LF1619-E/ML |
| PIC16LF1619-I/ML |
| PIC16LF1619T-I/ML |
| PIC16LF1703-E/ML |
| PIC16LF1703-I/ML |
| PIC16LF1703T-I/ML |
| PIC16LF1704-E/ML |
| PIC16LF1704-I/ML |
| PIC16LF1704T-I/ML |
| PIC16LF1705-E/ML |
| PIC16LF1705-I/ML |
| PIC16LF1705T-I/ML |
| PIC16LF1707-E/ML |
| PIC16LF1707-I/ML |
| PIC16LF1707T-I/ML |
| PIC16LF1708-E/ML |
| PIC16LF1708-I/ML |
| PIC16LF1708T-I/ML |
| PIC16LF1709-E/ML |
| PIC16LF1709-I/ML |
| PIC16LF1709T-I/ML |
| PIC16LF1713-E/ML |
| PIC16LF1713-I/ML |
| PIC16LF1713T-I/ML |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|--------------------|
| CATALOG_PART_NBR |
| PIC16LF1716-E/ML |
| PIC16LF1716-I/ML |
| PIC16LF1716T-I/ML |
| PIC16LF1717-E/ML |
| PIC16LF1717-I/ML |
| PIC16LF1717T-I/ML |
| PIC16LF1718-E/ML |
| PIC16LF1718-I/ML |
| PIC16LF1718T-I/ML |
| PIC16LF1719-E/ML |
| PIC16LF1719-I/ML |
| PIC16LF1719T-I/ML |
| PIC16LF1764-E/ML |
| PIC16LF1764-I/ML |
| PIC16LF1764T-I/ML |
| PIC16LF1765-E/ML |
| PIC16LF1765-I/ML |
| PIC16LF1765T-I/ML |
| PIC16LF1768-E/ML |
| PIC16LF1768-I/ML |
| PIC16LF1768T-I/ML |
| PIC16LF1769-E/ML |
| PIC16LF1769-I/ML |
| PIC16LF1769T-I/ML |
| PIC16LF1777-E/ML |
| PIC16LF1777-I/ML |
| PIC16LF1777T-I/ML |
| PIC16LF1779-E/ML |
| PIC16LF1779-I/ML |
| PIC16LF1779T-I/ML |
| PIC16LF1782-E/ML |
| PIC16LF1782-I/ML |
| PIC16LF1782T-I/ML |
| PIC16LF1783-E/ML |
| PIC16LF1783-I/ML |
| PIC16LF1783T-I/ML |
| PIC16LF1784-E/ML |
| PIC16LF1784-I/ML |
| PIC16LF1784T-I/ML |
| PIC16LF1786-E/ML |
| PIC16LF1786-I/ML |
| PIC16LF1786T-I/ML |
| PIC16LF1787-E/ML |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|----------------------|
| CATALOG_PART_NBR |
| PIC16LF1787-I/ML |
| PIC16LF1787T-I/ML |
| PIC16LF1788-E/ML |
| PIC16LF1788-I/ML |
| PIC16LF1788T-I/ML |
| PIC16LF1789-E/ML |
| PIC16LF1789-I/ML |
| PIC16LF1789T-I/ML |
| PIC16LF1823-E/ML |
| PIC16LF1823-I/ML |
| PIC16LF1823-I/MLC04 |
| PIC16LF1823-I/MLLS2 |
| PIC16LF1823T-I/ML |
| PIC16LF1823T-I/MLC04 |
| PIC16LF1823T-I/MLLS2 |
| PIC16LF1824-E/ML |
| PIC16LF1824-I/ML |
| PIC16LF1824-I/MLC01 |
| PIC16LF1824T-I/ML |
| PIC16LF1824T-I/MLC01 |
| PIC16LF1825-E/ML |
| PIC16LF1825-I/ML |
| PIC16LF1825T-E/ML |
| PIC16LF1825T-I/ML |
| PIC16LF1826-E/ML |
| PIC16LF1826-I/ML |
| PIC16LF1826T-I/ML |
| PIC16LF1827-E/ML |
| PIC16LF1827-I/ML |
| PIC16LF1827T-I/ML |
| PIC16LF1828-E/ML |
| PIC16LF1828-I/ML |
| PIC16LF1828T-I/ML |
| PIC16LF1828T-I/ML025 |
| PIC16LF1829-E/ML |
| PIC16LF1829-I/ML |
| PIC16LF1829T-I/ML |
| PIC16LF1847-E/ML |
| PIC16LF1847-I/ML |
| PIC16LF1847T-I/ML |
| PIC16LF1933-E/ML |
| PIC16LF1933-I/ML |
| PIC16LF1933T-I/ML |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|----------------------|
| CATALOG_PART_NBR |
| PIC16LF1934-E/ML |
| PIC16LF1934-I/ML |
| PIC16LF1934T-I/ML |
| PIC16LF1936-E/ML |
| PIC16LF1936-I/ML |
| PIC16LF1936T-I/ML |
| PIC16LF1936T-I/ML020 |
| PIC16LF1937-E/ML |
| PIC16LF1937-I/ML |
| PIC16LF1937T-I/ML |
| PIC16LF1938-E/ML |
| PIC16LF1938-I/ML |
| PIC16LF1938-I/MLC01 |
| PIC16LF1938T-E/ML |
| PIC16LF1938T-I/ML |
| PIC16LF1938T-I/MLC01 |
| PIC16LF1939-E/ML |
| PIC16LF1939-I/ML |
| PIC16LF1939T-I/ML |
| PIC16LF707-E/ML |
| PIC16LF707-I/ML |
| PIC16LF707T-I/ML |
| PIC16LF720-E/ML |
| PIC16LF720-I/ML |
| PIC16LF720T-I/ML |
| PIC16LF721-E/ML |
| PIC16LF721-I/ML |
| PIC16LF721T-I/ML |
| PIC16LF721T-I/ML022 |
| PIC16LF721T-I/ML024 |
| PIC16LF721T-I/ML025 |
| PIC16LF721T-I/ML028 |
| PIC16LF721T-I/ML030 |
| PIC16LF722A-E/ML |
| PIC16LF722A-I/ML |
| PIC16LF722AT-I/ML |
| PIC16LF722-E/ML |
| PIC16LF722-I/ML |
| PIC16LF722T-I/ML |
| PIC16LF723A-E/ML |
| PIC16LF723A-I/ML |
| PIC16LF723AT-I/ML |
| PIC16LF723-E/ML |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|----------------------|
| CATALOG_PART_NBR |
| PIC16LF723-I/ML |
| PIC16LF723T-I/ML |
| PIC16LF724-E/ML |
| PIC16LF724-I/ML |
| PIC16LF724T-I/ML |
| PIC16LF726-E/ML |
| PIC16LF726-I/ML |
| PIC16LF726T-I/ML |
| PIC16LF727-E/ML |
| PIC16LF727-I/ML |
| PIC16LF727-I/MLC01 |
| PIC16LF727T-I/ML |
| PIC16LF727T-I/MLC01 |
| PIC18F13K22-E/ML |
| PIC18F13K22-E/MLC01 |
| PIC18F13K22-I/ML |
| PIC18F13K22T-I/ML |
| PIC18F13K22T-I/ML020 |
| PIC18F14K22-E/ML |
| PIC18F14K22-I/ML |
| PIC18F14K22T-E/ML |
| PIC18F14K22T-I/ML |
| PIC18F23K20-E/ML |
| PIC18F23K20-I/ML |
| PIC18F23K20T-E/ML |
| PIC18F23K20T-I/ML |
| PIC18F23K22-E/ML |
| PIC18F23K22-I/ML |
| PIC18F23K22T-E/ML |
| PIC18F23K22T-I/ML |
| PIC18F24K20-E/ML |
| PIC18F24K20-I/ML |
| PIC18F24K20T-I/ML |
| PIC18F24K20T-I/ML028 |
| PIC18F24K22-E/ML |
| PIC18F24K22-I/ML |
| PIC18F24K22T-E/ML |
| PIC18F24K22T-I/ML |
| PIC18F24K50-E/ML |
| PIC18F24K50-I/ML |
| PIC18F24K50T-I/ML |
| PIC18F25K20-E/ML |
| PIC18F25K20-I/ML |

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Affected Catalog Part Numbers (CPN)

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|----------------------|
| PCN_JAON-12WMVJ562 |
| CATALOG_PART_NBR |
| PIC18F25K20-I/MLC02 |
| PIC18F25K20-I/MLC05 |
| PIC18F25K20-I/MLC10 |
| PIC18F25K20-I/MLLPR |
| PIC18F25K20T-E/ML |
| PIC18F25K20T-I/ML |
| PIC18F25K20T-I/MLC02 |
| PIC18F25K20T-I/MLC10 |
| PIC18F25K22-E/ML |
| PIC18F25K22-I/ML |
| PIC18F25K22T-E/ML |
| PIC18F25K22T-I/ML |
| PIC18F25K50-E/ML |
| PIC18F25K50-I/ML |
| PIC18F25K50T-E/ML |
| PIC18F25K50T-E/ML020 |
| PIC18F25K50T-E/ML022 |
| PIC18F25K50T-I/ML |
| PIC18F25K80-E/MM |
| PIC18F25K80-E/MMC01 |
| PIC18F25K80-H/MM |
| PIC18F25K80-I/MM |
| PIC18F25K80-I/MMC02 |
| PIC18F25K80-I/MMC04 |
| PIC18F25K80T-E/MM |
| PIC18F25K80T-E/MMC01 |
| PIC18F25K80T-E/MMCUI |
| PIC18F25K80T-H/MM |
| PIC18F25K80T-I/MM |
| PIC18F25K80T-I/MMC02 |
| PIC18F25K80T-I/MMC04 |
| PIC18F26K20-E/ML |
| PIC18F26K20-I/ML |
| PIC18F26K20-I/ML035 |
| PIC18F26K20-I/MLC03 |
| PIC18F26K20T-E/ML |
| PIC18F26K20T-I/ML |
| PIC18F26K20T-I/ML033 |
| PIC18F26K20T-I/ML034 |
| PIC18F26K20T-I/ML035 |
| PIC18F26K20T-I/ML036 |
| PIC18F26K20T-I/ML040 |
| PIC18F26K20T-I/ML043 |

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Affected Catalog Part Numbers (CPN)

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|----------------------|
| PCN_JAON-12WMVJ562 |
| CATALOG_PART_NBR |
| PIC18F26K20T-I/MLC03 |
| PIC18F26K22-E/ML |
| PIC18F26K22-I/ML |
| PIC18F26K22T-E/ML |
| PIC18F26K22T-I/ML |
| PIC18F26K22T-I/ML024 |
| PIC18F26K80-E/MM |
| PIC18F26K80-H/MM |
| PIC18F26K80-I/MM |
| PIC18F26K80T-E/MM |
| PIC18F26K80T-I/MM |
| PIC18F26K80T-I/MM023 |
| PIC18F26K80T-I/MM025 |
| PIC18F43K20-E/ML |
| PIC18F43K20-I/ML |
| PIC18F43K20T-I/ML |
| PIC18F43K22-E/ML |
| PIC18F43K22-I/ML |
| PIC18F43K22T-I/ML |
| PIC18F44K20-E/ML |
| PIC18F44K20-I/ML |
| PIC18F44K20T-I/ML |
| PIC18F44K22-E/ML |
| PIC18F44K22-I/ML |
| PIC18F44K22T-I/ML |
| PIC18F45K20-E/ML |
| PIC18F45K20-I/ML |
| PIC18F45K20-I/MLC01 |
| PIC18F45K20-I/MLC05 |
| PIC18F45K20T-I/ML |
| PIC18F45K20T-I/MLC01 |
| PIC18F45K20T-I/MLC05 |
| PIC18F45K22-E/ML |
| PIC18F45K22-I/ML |
| PIC18F45K22T-I/ML |
| PIC18F45K80-E/ML |
| PIC18F45K80-H/ML |
| PIC18F45K80-I/ML |
| PIC18F45K80T-E/ML |
| PIC18F45K80T-I/ML |
| PIC18F46K20-E/ML |
| PIC18F46K20-I/ML |
| PIC18F46K20T-E/ML |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|-----------------------|
| CATALOG_PART_NBR |
| PIC18F46K20T-I/ML |
| PIC18F46K22-E/ML |
| PIC18F46K22-I/ML |
| PIC18F46K22T-E/ML |
| PIC18F46K22T-I/ML |
| PIC18F46K80-E/ML |
| PIC18F46K80-H/ML |
| PIC18F46K80-I/ML |
| PIC18F46K80T-E/ML |
| PIC18F46K80T-I/ML |
| PIC18LF13K22-E/ML |
| PIC18LF13K22-I/ML |
| PIC18LF13K22T-I/ML |
| PIC18LF14K22-E/ML |
| PIC18LF14K22-I/ML |
| PIC18LF14K22T-E/ML |
| PIC18LF14K22T-E/ML021 |
| PIC18LF14K22T-I/ML |
| PIC18LF23K22-E/ML |
| PIC18LF23K22-I/ML |
| PIC18LF23K22T-I/ML |
| PIC18LF23K22T-I/ML020 |
| PIC18LF23K22T-I/ML021 |
| PIC18LF24K22-E/ML |
| PIC18LF24K22-I/ML |
| PIC18LF24K22T-I/ML |
| PIC18LF24K50-E/ML |
| PIC18LF24K50-I/ML |
| PIC18LF24K50T-I/ML |
| PIC18LF25K22-E/ML |
| PIC18LF25K22-I/ML |
| PIC18LF25K22T-I/ML |
| PIC18LF25K50-E/ML |
| PIC18LF25K50-I/ML |
| PIC18LF25K50T-I/ML |
| PIC18LF25K80-I/MM |
| PIC18LF25K80T-I/MM |
| PIC18LF26K22-E/ML |
| PIC18LF26K22-I/ML |
| PIC18LF26K22-I/MLC04 |
| PIC18LF26K22-I/MLC05 |
| PIC18LF26K22-I/MLC06 |
| PIC18LF26K22T-E/ML |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-12WMVJ562 |
|-----------------------|
| CATALOG_PART_NBR |
| PIC18LF26K22T-I/ML |
| PIC18LF26K22T-I/ML024 |
| PIC18LF26K22T-I/MLC04 |
| PIC18LF26K22T-I/MLC05 |
| PIC18LF26K22T-I/MLC06 |
| PIC18LF26K80-I/MM |
| PIC18LF26K80T-I/MM |
| PIC18LF43K22-E/ML |
| PIC18LF43K22-I/ML |
| PIC18LF43K22T-I/ML |
| PIC18LF44K22-E/ML |
| PIC18LF44K22-I/ML |
| PIC18LF44K22T-I/ML |
| PIC18LF45K22-E/ML |
| PIC18LF45K22-I/ML |
| PIC18LF45K22T-I/ML |
| PIC18LF45K80-I/ML |
| PIC18LF45K80T-I/ML |
| PIC18LF46K22-E/ML |
| PIC18LF46K22-I/ML |
| PIC18LF46K22T-I/ML |
| PIC18LF46K80-I/ML |
| PIC18LF46K80T-I/ML |
| PIC24F08KA102-E/ML |
| PIC24F08KA102-I/ML |
| PIC24F08KL302-E/ML |
| PIC24F08KL302-I/ML |
| PIC24F08KL402-I/ML |
| PIC24F08KM202-I/ML |
| PIC24F16KA102-E/ML |
| PIC24F16KA102-I/ML |
| PIC24F16KA102T-I/ML |
| PIC24F16KA302-I/ML |
| PIC24F16KA302T-I/ML |
| PIC24F16KA304-I/ML |
| PIC24F16KA304T-I/ML |
| PIC24F16KL402-E/ML |
| PIC24F16KL402-I/ML |
| PIC24F16KL402T-I/ML |
| PIC24F16KM102-I/ML |
| PIC24F16KM202-E/ML |
| PIC24F16KM202-I/ML |
| PIC24F16KM204-E/ML |

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Affected Catalog Part Numbers (CPN)

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|----------------------|
| PCN_JAON-12WMVJ562 |
| CATALOG_PART_NBR |
| PIC24F16KM204-I/ML |
| PIC24F32KA302-E/ML |
| PIC24F32KA302-I/ML |
| PIC24F32KA302T-E/ML |
| PIC24F32KA302T-I/ML |
| PIC24F32KA304-E/ML |
| PIC24F32KA304-I/ML |
| PIC24F32KA304T-I/ML |
| PIC24FV08KM202-I/ML |
| PIC24FV08KM204-I/ML |
| PIC24FV16KA302-I/ML |
| PIC24FV16KA302T-I/ML |
| PIC24FV16KA304-I/ML |
| PIC24FV16KA304T-I/ML |
| PIC24FV16KM102-I/ML |
| PIC24FV16KM104-I/ML |
| PIC24FV16KM202-E/ML |
| PIC24FV16KM202-I/ML |
| PIC24FV16KM202T-I/ML |
| PIC24FV16KM204-I/ML |
| PIC24FV32KA302-I/ML |
| PIC24FV32KA302T-I/ML |
| PIC24FV32KA304-E/ML |
| PIC24FV32KA304-I/ML |
| PIC24FV32KA304T-I/ML |
| UTC2000/MG |
| UTC2000-E/MG |
| UTC2000-I/MG |
| UTC2000T/MG |
| UTC2000T-E/MG |
| UTC2000T-I/MG |